**Section 307.2307 Electroless Plating**

a) Applicability. This Section applies to discharges resulting from the electroless plating of a metallic layer on a metallic or nonmetallic substrate.

b) Specialized Definitions. The Board incorporates by reference 40 CFR 413.71 (2003). This incorporation includes no later amendments or editions.

c) Existing Sources

1) The Board incorporates by reference 40 CFR 413.74 (2003). This incorporation includes no later amendments or editions.

2) No person subject to the pretreatment standards incorporated by reference in subsection (c)(1) may cause, threaten, or allow the discharge of any contaminant to a POTW in violation of those standards.

d) Sources whose construction commenced after August 31, 1982 are subject to Subpart BH.

(Source: Amended at 47 Ill. Reg. 4662, effective March 23, 2023)